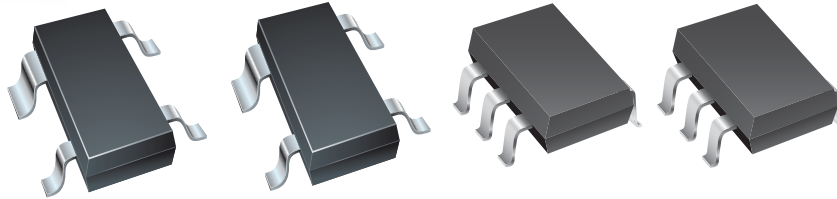


Product Change Notification

CHIP DIODES



September, 2015 -
REVISED OCTOBER, 2015

Change to Die Attach Material and Application Process for Bourns® Model CD143A-SR05, CD143A-SR12, CDSOT23-SRV05-4 and CDSOT23-SR208 TVS Diode Array Series

In order to support our fast growing demand, Bourns is making a change to the die attach material and its application process for the Bourns® Model [CD143A-SR05](#), [CD143A-SR12](#), [CDSOT23-SRV05-4](#) and [CDSOT23-SR208](#) TVS Diode Array Series. This change will help improve the reproducibility of the adhesive fillet. A conductive die attach film (CDAF) will be used in place of the current conductive epoxy. There are no changes to the data sheet ratings or electrical characteristics.

The change to the die attach material and its application process has no impact on the fit, form or function of the product. The product marking and label will remain unchanged.

Evaluation samples and qualification data are available upon request. For clarification, beginning April 1, 2016, customers may receive products using the CDAF.

Implementation dates are as follows:

Date that manufacturing of existing product will cease: March 31, 2016

Bourns will begin phasing in this process: April 1, 2016

First date code using the above changes: 1613

If you have any questions or need additional information, please feel free to contact [Customer Service/ Inside Sales](#).